

Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

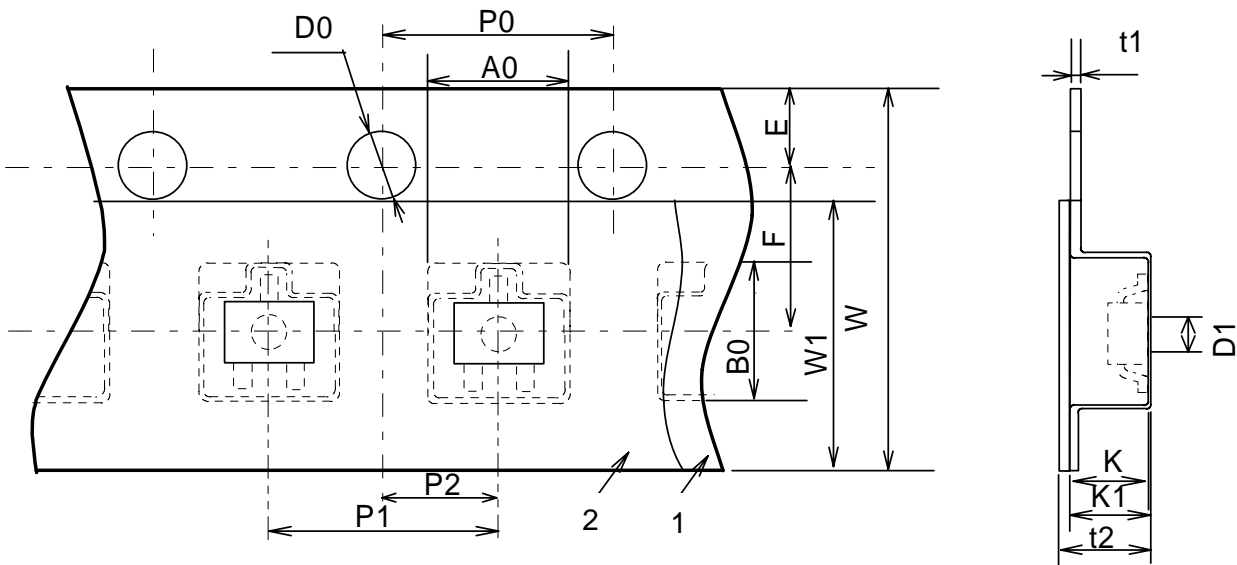
| | | | |
|------------------|----------------------------------|-------------|------|
| Reference | Tape and reel information | Mini3-G3-B | |
| | | Total pages | page |
| | | 2 | 1 |

1. Taping quantity

The standard quantity shall be 3000 pcs / reel.

2. Taping form and dimensions

Unit : mm



1. Carrier tape
2. Cover tape

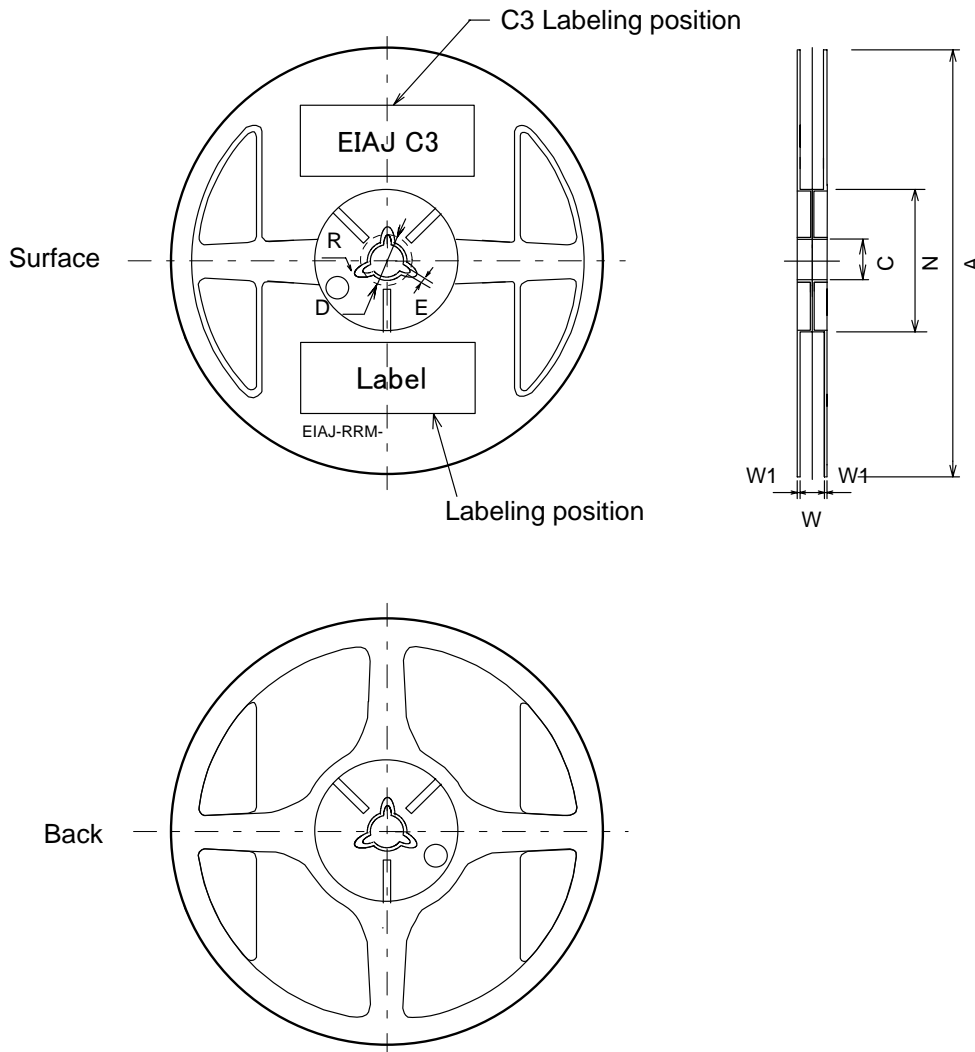
| Item | | Symbol | Dimensions | Remarks |
|--|--------------|--------|---------------|--------------------------------------|
| Dented square hole for product insertion | Length | A0 | 3.2 ± 0.1 | |
| | Width | B0 | 3.3 ± 0.1 | |
| | Depth | K | 1.35 ± 0.10 | |
| | Pitch | P1 | 4.0 ± 0.1 | Accumulated error ±0.2max/10 pitches |
| Sprocket hole | Diameter | D0 | 1.5+0.1/-0.0 | |
| | Pitch | P0 | 4.0 ± 0.1 | Accumulated error ±0.2max/10 pitches |
| | Position | E | 1.75 ± 0.10 | |
| Embossing hole | Diameter | D1 | 1.0 +0.3/-0.0 | |
| Center-to-center distance | Longitudinal | P2 | 2.00 ± 0.05 | |
| | Traverse | F | 3.50 ± 0.05 | |
| Cover tape | Width | W1 | 5.4 ± 0.1 | |
| Carrier tape | Width | W | 8.0 ± 0.3 | |
| | Thickness | t1 | 0.25 ± 0.10 | |
| Hole outer depth | | K1 | 1.4 ± 0.1 | |
| Total thickness | | t2 | 1.5 ± 0.1 | |

Note : 1) Radius at each corner shall be 0.25R or less.

| | | | |
|------------------|----------------------------------|-------------|------|
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3. Reel and dimensions

Unit:mm



| Item | | Symbol | Dimensions | Remarks | |
|-----------------------------|--------------------------|---|----------------|----------|--|
| Flange | Diameter | A | 180.0+0.0/-3.0 | | |
| | Thickness | W1 | 1.2 | | |
| | Distance between flanges | W | 9.0±0.3 | | |
| Hub | Outer diameter | N | 60.0+1.0/-0.0 | | |
| | Spindle hole diameter | C | 13.0±0.2 | | |
| | Keyway | Width | E | 2.0±0.5 | |
| | | Depth | D | 21.0±0.8 | |
| | Radius at corner | R | 1.0 | | |
| Indication of the name, etc | | To be printed on one side of flange. Name, Quantity, Serial No, etc. to be shown | | | |

| | | |
|-------------|-----------|--|
| 2009.4.28 | 2012.6.22 | |
| Established | Revised | |

Request for your special attention and precautions in using the technical information and semiconductors described in this book

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